

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
HARUNOBU KONDO	04/05/2022
KAZUTERU ISHIZUKA	04/05/2022
WATARU NOBEHARA	04/05/2022
RYOSUKE YATSUSHIRO	04/05/2022
MAKOTO SAITO	04/05/2022
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	MICRON TECHNOLOGY, INC.
<b>Street Address:</b>	8000 SOUTH FEDERAL WAY
<b>City:</b>	BOISE
<b>State/Country:</b>	IDAHO
<b>Postal Code:</b>	83716-9632
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	17714797
<b>CORRESPONDENCE DATA</b>	
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<b>ATTORNEY DOCKET NUMBER:</b>	P297208US01
<b>NAME OF SUBMITTER:</b>	DENISE SHERIDAN
<b>SIGNATURE:</b>	/Denise Sheridan/
<b>DATE SIGNED:</b>	04/06/2022
<b>Total Attachments: 2</b>	
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Harunobu Kondo, Kazuteru Ishizuka,  
Wataru Nobehara, Ryosuke Yatsushiro and  
Makoto Saito

Docket No. P297208.US.01

Disclosure No. 2021141063-US

Filed : Concurrently herewith

For : SEMICONDUCTOR DEVICE  
HAVING L-SHAPED CONDUCTIVE  
PATTERN

ASSIGNMENT :

☒ Enclosed for recording

☐ Previously recorded

Date: \_\_\_\_\_

Reel: \_\_\_\_\_

FOR GOOD AND VALUABLE CONSIDERATION, the receipt, sufficiency and adequacy of which are hereby acknowledged, the undersigned do hereby:

SELL, ASSIGN AND TRANSFER to **Micron Technology, Inc.** (the "Assignee"), a corporation of Delaware, having a place of business at 8000 South Federal Way, Boise, Idaho 83716-9632, the entire right, title and interest for the United States and all foreign countries, in and to any and all improvements which are disclosed in the application for United States Letters Patent, which has been executed by the undersigned concurrently herewith and is entitled "**SEMICONDUCTOR DEVICE HAVING L-SHAPED CONDUCTIVE PATTERN**"; such application and all divisional, continuing, substitute, renewal, reissue and all other applications for patent which have been or shall be filed in the United States and all foreign countries on any of such improvements; all original and reissued patents which have been or shall be issued in the United States and all foreign countries on such improvements; and specifically including the right to file foreign applications under the provisions of any convention or treaty and claim priority based on such application in the United States of America;

AUTHORIZE AND REQUEST the issuing authority to issue any and all United States and foreign patents granted on such improvements to the Assignee;

WARRANT AND COVENANT that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been or will be made to others by the undersigned, and that the full right to convey the same as herein expressed is possessed by the undersigned;

COVENANT that, when requested and at the expense of the Assignee, to carry out in good faith the intent and purpose of this assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all such improvements; execute all rightful oaths, declarations, assignments, powers of attorney and other papers; communicate to the Assignee all facts known to the undersigned relating to such improvements and the history thereof; and generally do everything possible which the Assignee shall consider desirable for securing, maintaining and enforcing proper patent protection for such improvements and for vesting title to such improvements in the Assignee;

TO BE BINDING on the heirs, assigns, representatives and successors of the undersigned and extend to the successors, assigns and nominees of the Assignee.

Signature: Harunobu Kondo

Date: 2022/04/05  
(YYYY-MM-DD)

Assignor Name: Harunobu Kondo

Signature: Kazuteru Ishizuka

Date: 2022/04/05  
(YYYY-MM-DD)

Assignor Name: Kazuteru Ishizuka

Signature: Wataru Nobehara

Date: 2022/04/05  
(YYYY-MM-DD)

Assignor Name: Wataru Nobehara

Signature: Ryosuke Yatsushiro

Date: 2022/04/05  
(YYYY-MM-DD)

Assignor Name: Ryosuke Yatsushiro

Signature: Makoto Saito

Date: 2022/04/05  
(YYYY-MM-DD)

Assignor Name: Makoto Saito